

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

KUMADA et al.

Application No. Unassigned

Art Unit: Unassigned

Filed: July 22, 2003

Examiner: Unassigned

For: VIA-FILLING MATERIAL AND
PROCESS FOR FABRICATING
SEMICONDUCTOR INTEGRATED
CIRCUIT USING THE SAME

PRELIMINARY AMENDMENT

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Prior to the examination of the above-identified patent application, please enter the following amendments and consider the following remarks.